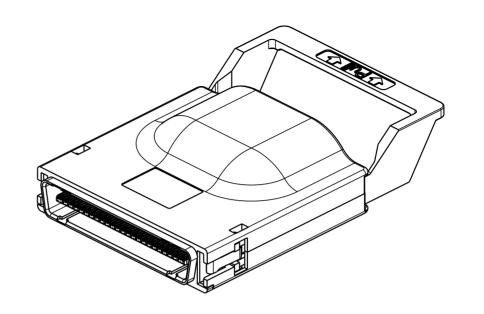
3 PRODUCT NUMBER 10010264-001 ↑INd分 10010264-001LF -21.249.0 -10.3NOTES: 48.8 I. MATES WITH FCI RECEPTACLES 58366 OR 58367. S48 S 2 (2.) MATERIALS: BLOCKER - ALUMINUM ALLOY BACKSHELL - ZINC ALLOY, NICKEL PLATING OVER COPPER CONNECTOR - THERMOPLASTIC AND COPPER ALLOY LATCH - THERMOPLASTIC AND STAINLESS STEEL PRINTED CIRCUIT BOARD - FR4 FIBERGLASS 3. PRODUCT SPECIFICATION: GS-12-209. S47 SΙ tolerance projection A MM www.fciconnect.com ASME YI4.5 FCI ASME YI4.5 Dr PC Product family 07/09/02 EYEMAX(†m) Scale size revecn no date Eng N.LEE 07/09/02 Spec ref 13:10 CY21121 PC 07/09/02 Chr PC 07/09/02 V05-0542 Material SEE NOTES ECN TOLERANCES UNLESS OTHERWISE SPECIFIED В CY21256 PC 11/22/02 Appr N.LEE 07/09/02 GL 06/17/03 CY31444 D V03-1234 DAI 12/05/03 12X EYEMAX Rev 10010264 LINEAR ±.10 V04-0483 DAI 06/17/04 LOOPBACK MODULE 0.XXX ±.050 V05-0064 TAB 03/07/05 V05-0542 TAB 06/17/05 catalog no CUSTOMER ANGULAR sheet I of 2 PDM: Rev:G STATUSReleased 4 Printed: Jul 22, 2010

PRODUCT NUMBER 10010264-001 10010264-001LF

PIN CONNECTIONS							
FROM		TO					
PIN NO.	SIGNAL	PIN NO.	SIGNAL				
\$1	IBtxlp(0)	\$48	IBtxOp(0)				
\$2	IBtxIn(0)	\$47	IBtxOn(0)				
\$3	IBtxlp(I)	\$46	IBtxOp(I)				
S 4	IBtxIn(I)	\$45	IBtxOn(I)				
\$5	IBtxlp(2)	\$44	IBtxOp(2)				
\$6	IBtxIn(2)	\$43	IBtxOn(2)				
S 7	IBtxlp(3)	\$42	IBtxOp(3)				
\$8	IBtxIn(3)	\$41	IBtxOn(3)				
\$9	IBtxlp(4)	\$40	IBtxOp(4)				
\$10	IBtxIn(4)	\$39	IBtxOn(4)				
SII	IBtxlp(5)	\$38	IBtxOp(5)				
\$12	IBtxIn(5)	\$37	IBtxOn(5)				
\$13	IBtxlp(6)	\$36	IBtxOp(6)				
\$14	IBtxIn(6)	\$35	IBtxOn(6)				
\$15	IBtxlp(7)	\$34	IBtxOp(7)				
\$16	IBtxIn(7)	\$33	IBtxOn(7)				
S I 7	IBtxlp(8)	\$32	IBtxOp(8)				
\$18	IBtxIn(8)	\$31	IBtxOn(8)				
\$19	IBtxlp(9)	\$30	IBtxOp(9)				
\$20	IBtxIn(9)	\$29	IBtxOn(9)				
\$21	IBtxlp(10)	\$28	IBtxOp(10)				
\$22	IBtxIn(IO)	\$27	IBtxOn(10)				
\$23	IBtxlp(II)	\$26	IBtxOp(II)				
\$24	IBtxIn(II)	\$25	IBtxOn(II)				



LEAD FREE NOTES:

- I. LEAD FREE SOLDER TAIL PLATING 2μm(80μin) MIN MATTE TIN OVER 1.27μm(50μin) MIN NICKEL UNDERPLATE.
- 2. IF LEAD FREE PART NUMBER, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MIN THICK CIRCUIT BOARD.
- 3. PACKAGING OF LEAD FREE PRODUCTS MEETS LABELING AND PACKAGING SPECIFICATION GS-14-920.
- 4. LEAD FREE PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

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A	12X EYEMAX LOOPBACK MODULE		ou 6mp	100102	6 4	Rev.	
Pro/F file	catalog no	-	t	CUSTOMER	sheet 2 of	2	1